

# Von unseren Partnern im Ausland

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## **MEDEA+ Leading Edge Innovations for Europe**

Latest innovations in micro/nanoelectronic technologies as well as their exploitation by means of intelligent solutions in applications and systems have proved that EUREKA's cluster MEDEA+ is one of Europe's most powerful programmes in R&D, in keeping the region ahead of competition. The close collaboration of chip manufacturers, their customers as well as equipment suppliers, supported by research institutes and academia, ensures that Europe maintains its global position in a cornerstone industry.

In a series of projects to develop basic fabrication processes for integrated circuits meeting the demands for ever smaller and more highly performing electronic systems, MEDEA+ partners substantially contributed to the 90 nm node (now in mass production), thus paving the way for successful prototyping of 65 nm technology. The 65 nm process has been established with significant yield improvement and reliability meeting specifications and is now ready for the manufacture of prototype customer chips. The chipmaking partners will be sharing their 65 nm cell libraries and IP blocks



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[www.medeaplus.org](http://www.medeaplus.org)

In order to continue innovative projects and successful achievements in R&D, MEDEA+ will launch a new call for submitting project proposals in the last quarter of 2006. The next call will be announced in due course on our website [www.medeaplus.org](http://www.medeaplus.org)

and are confident about the successful start of the process in full production copying customer's demand. But in order to maintain Europe's lead in CMOS integrated circuit manufacture, MEDEA+ partners are already looking ahead to develop advanced process modules and transistor architectures for the 45 nm node technology in industrial 300 mm wafer fabrication plants. Europe is keen to be able to propose the most advanced logic technologies ahead of the globally predicted roadmap, boosting the position of Europe's chipmakers and their equipment and material suppliers in the world market.

Focused research in the EUREKA MEDEA+ cluster has also ensured a world lead for Europe in next-generation photolithography, a key enabling technology for integrated circuit fabrication. MEDEA+ EUV (Extreme UltraViolet) Lithography projects covered four main elements of the litho process: tools, masks, illumination sources and processing. The recently ended projects have achieved remarkable technological results, showing that Europe's EUV Lithography is now solid number one worldwide, impressing US and Asian competitors and potential customers alike.

A typical success story in the domain of applications are the recent achievements made in Smartcard technology. Smartcards are so-called because of the microprocessor chips embedded in them that can hold and process data. Eleven partner companies from 3 different countries succeeded to deliver the hardware and software to form a basis for open platforms permitting the development of secure value-added services in telecommunications, banking, pay-TV, health and other sectors. Basic technological building blocks to high-speed wireless and contactless protocols were defined as well. The project breakthrough allows the consortium to exploit the card-based e-commerce market, currently estimated at 20 billion euros in Europe. With its wide vertical partnership and global reach, this project has become the flagship for all EUREKA Smartcard projects. (Laaf)



Cont@ct:  
Barry Sullivan, Director,  
International Engineering Consortium,  
fon: 001 312 559 3302,  
[bsullivan@iec.org](mailto:bsullivan@iec.org)



Weitere Informationen über  
das EDA Consortium finden Sie  
unter [www.edac.org](http://www.edac.org).

**Ansprechpartner  
zu dieser Rubrik:**

Ralf Popp  
fon: 0511 762-19697  
[popp@edacentrum.de](mailto:popp@edacentrum.de)

#### EDA Consortium Elects New Officers and Board

SAN JOSE, California, June 1, 2006 —The Electronic Design Automation (EDA) Consortium announced that it has elected a nine-member Board of Directors and officers to serve the organization through spring 2008. Aart de Geus, Ph.D., chairman and CEO of Synopsys, Inc., was elected as chairman by the new board. Kathryn Kranen, president and CEO of Jasper Design Automation, and past chairman Walden C. Rhines, chairman and CEO of Mentor Graphics, were elected as vice-chairmen.

In addition to the officers, the elected EDA Consortium Board members include: John Bourgoin, president and CEO, MIPS Technologies; Michael J. Fister, president

and CEO, Cadence Design Systems; John Kibarian, CEO, president and co-founder, PDF Solutions; Alan Naumann, president and CEO, CoWare; Scott Sandler, president and CEO, Novas Software and Sanjay Srivastava, president and CEO, Denali Software.

"I am looking forward to working with my Board colleagues to set the upcoming agenda for the EDAC based on the challenges and opportunities our industry faces in the coming years," stated de Geus. "EDA plays a critical role in the semiconductor value chain, and our customers recognize the importance of EDA to their successful technology development and, ultimately, the bottom line. Collectively, we can advance the industry and make certain we address the growing yield and productivity challenges faced by our customers as they move to meet their own customers' demands."

The new board was elected by the EDA Consortium's general membership at their biannual election meeting on Wednesday, May 31. The new board chairman was elected at a special board meeting held following the election meeting. At the same meeting, the Board also reappointed Robert M. Gardner CFO and Treasurer and Mark White, Partner, White & Lee, LLP, Corporate Secretary. Pamela Parrish continues in her role as Executive Director.

#### Absage: EuroDesignCon 2006

In the latest issue, we announced that Barry Sullivan, Director at the International Engineering Consortium (IEC), would give an interview concerning Euro DesignCon 2006. Recently, he regretfully announced that the IEC will not produce a Euro DesignCon program in 2006. Therefore, the interview has been cancelled.

The IEC has staged Euro DesignCon in Munich for the past two years as a sister event of the very successful Santa-Clara based DesignCon program. This effort has been an outgrowth of the Consortium's commitment to broaden the access to the DesignCon program for the semiconductor and electronics industry.

While the initiative has succeeded in some ways, in other ways the event fell short of overall industry objectives. Consequently, the IEC will not conduct Euro DesignCon in 2006. Nonetheless, the IEC intends to continue to explore ways to meet their objective of broader access for electronic design engineers and executives to education and professional development provided by the IEC. (Pp)